

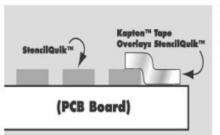
User Instructions

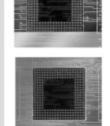


1. Remove part.

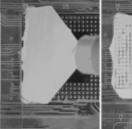


Dress site by wicking off residual solder with solder wick or de-soldering tool.





7. Tape off the area around the periphery of the part site with Kapton™ tape. NOTE: Ensure that the tape overlaps the outside edge of the StencilQuik™.







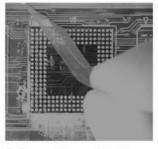
 Squeegee solder paste across the top of the StencilQuik™ making sure all of the apertures are filled.



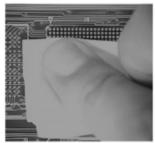
3. Clean site.



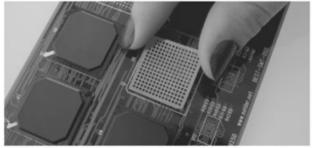
 Remove release liner from back of SolderQuikTM stencil.



Remove the masking tape applied to the periphery of Ithe reworked area applied in step #7.



 Wipe off the excess solder paste from the top of the Stencilquik™ with a lintfree wipe.



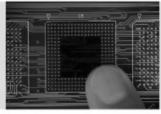
5. Align StencilQuik™ by positioning the diagonally opposite corner apertures over the corresponding pads. *NOTE: Ensure that the pads are centered in the apertures.*



11. Gently place the properly conditioned part aligning the balls or leads of the part with the filled apertures.



12. Reflow the part.



 Place the StencilQuik™ on the board applying pressure to the stencil to activate the adhesive. NOTE: Do not apply pressure until satisfied with alignment.



BEST

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